

# Surface Mount Schottky Power Rectifier SMB Power Surface Mount Package

## MBRS1540T3

These devices employ the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

### Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guard-Ring for Over-Voltage Protection
- Low Forward Voltage Drop
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Mechanical Characteristics

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	40	V
Average Rectified Forward Current (At Rated $V_R$ , $T_C = 100^\circ\text{C}$ )	$I_O$	1.5	A
Peak Repetitive Forward Current (At Rated $V_R$ , Square Wave, 100 kHz, $T_C = 105^\circ\text{C}$ )	$I_{FRM}$	3.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	40	A
Storage/Operating Case Temperature	$T_{stg}$ , $T_C$	-55 to +150	°C
Operating Junction Temperature	$T_J$	-55 to +125	°C
Voltage Rate of Change (Rated $V_R$ , $T_J = 25^\circ\text{C}$ )	$dv/dt$	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### SCHOTTKY BARRIER RECTIFIER 1.5 AMPERES, 40 VOLTS



SMB  
CASE 403A

### MARKING DIAGRAM



- BGJ = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 WW = Work Week  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MBRS1540T3G	SMB (Pb-Free)	2500/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# MBRS1540T3

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1)	$R_{\theta JL}$	24	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	80	

## ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 3) see Figure 2	$V_F$	$T_J = 25^\circ\text{C}$	$T_J = 125^\circ\text{C}$	V
		0.46	0.39	
Maximum Instantaneous Reverse Current (Note 3) see Figure 4	$I_R$	$T_J = 25^\circ\text{C}$	$T_J = 100^\circ\text{C}$	mA
		0.8	5.7	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Mounted with minimum recommended pad size, PC Board FR4.
2. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.
3. Pulse Test: Pulse Width  $\leq 250 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

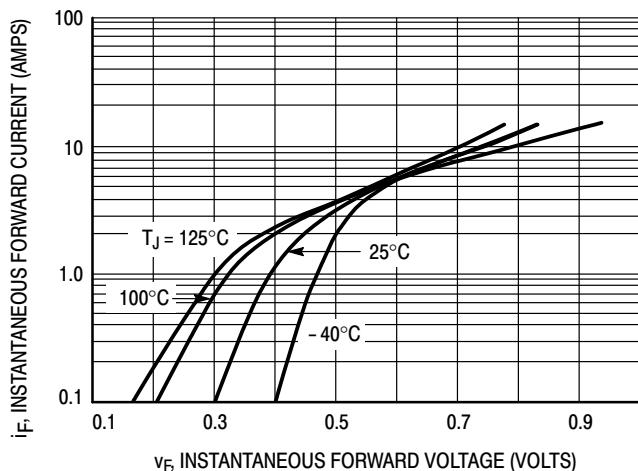


Figure 1. Typical Forward Voltage

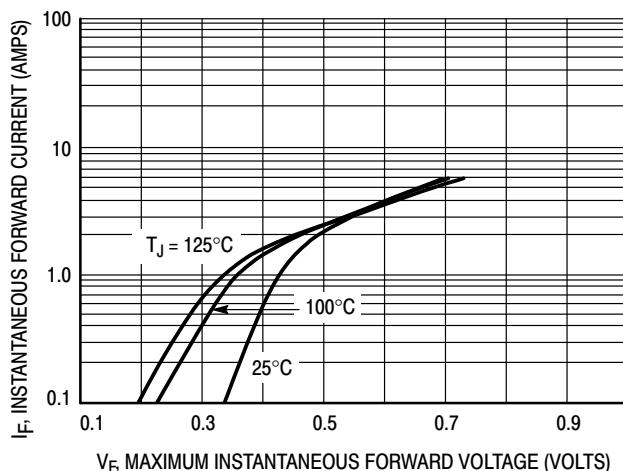


Figure 2. Maximum Forward Voltage

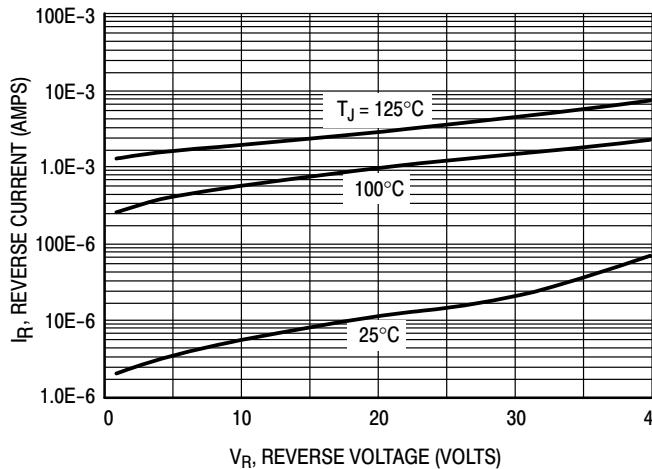


Figure 3. Typical Reverse Current

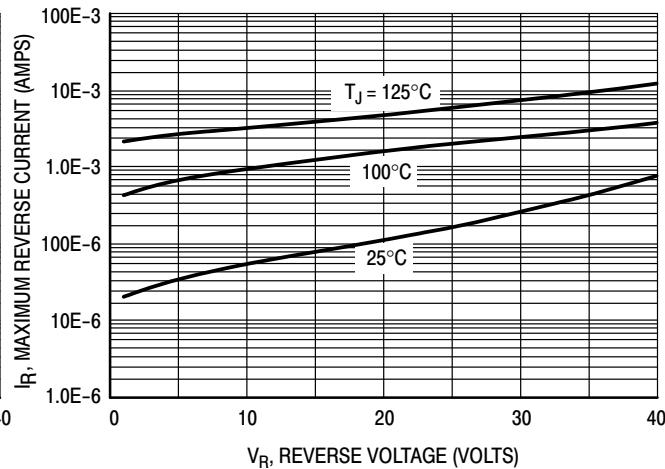


Figure 4. Maximum Reverse Current

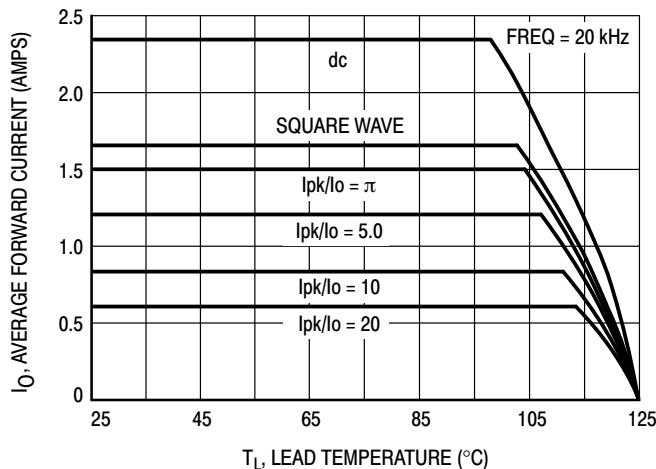


Figure 5. Current Derating

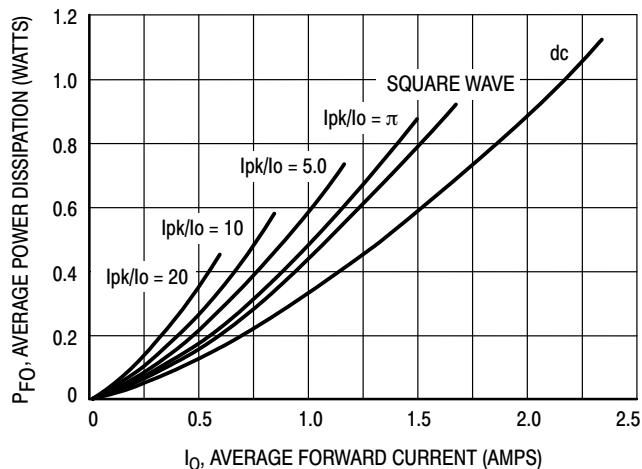
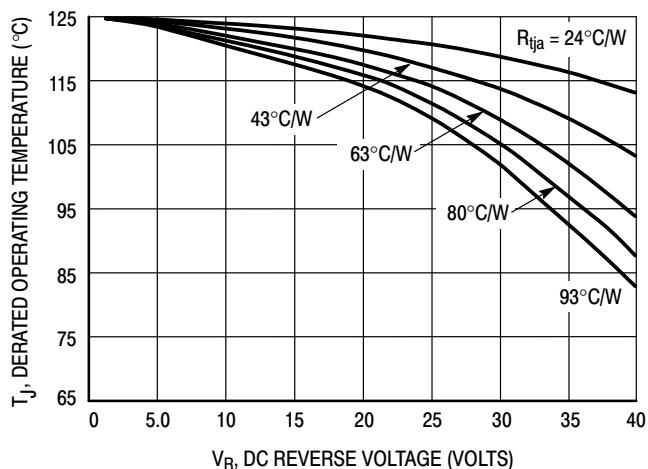
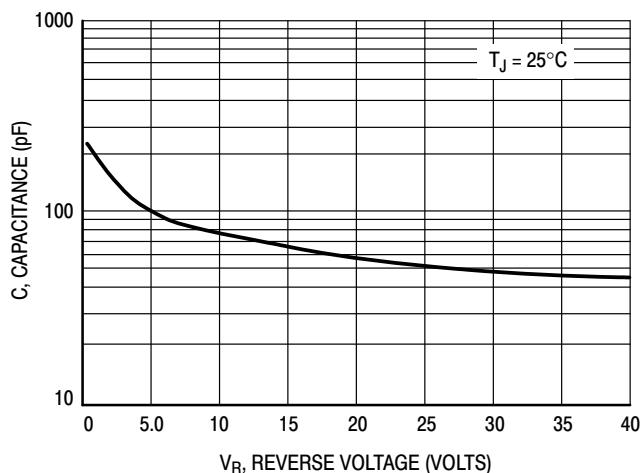


Figure 6. Forward Power Dissipation

# MBRS1540T3



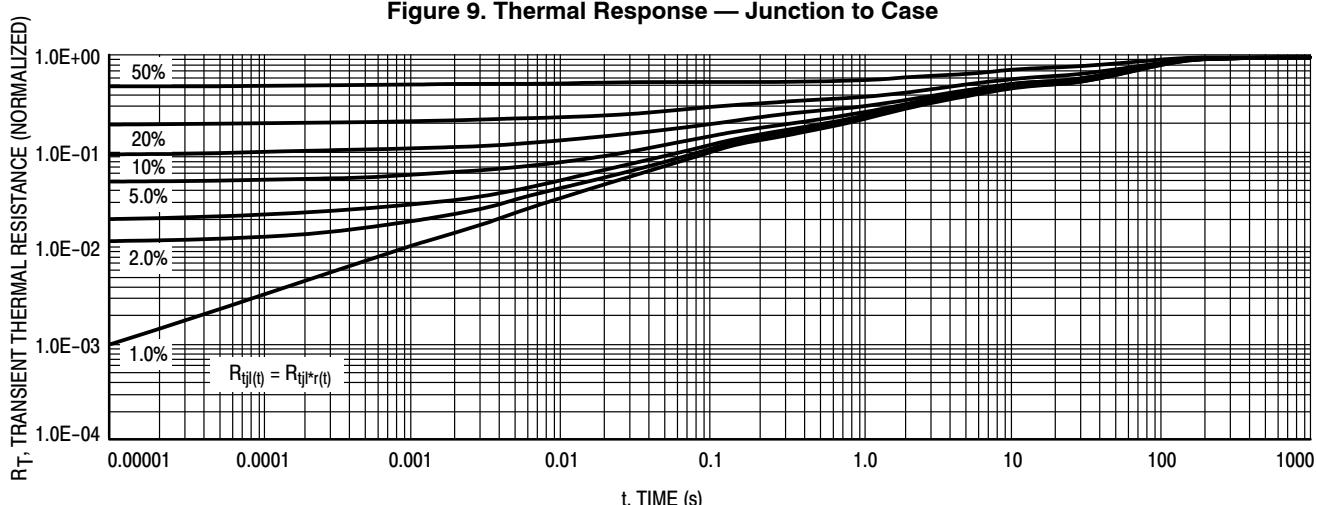
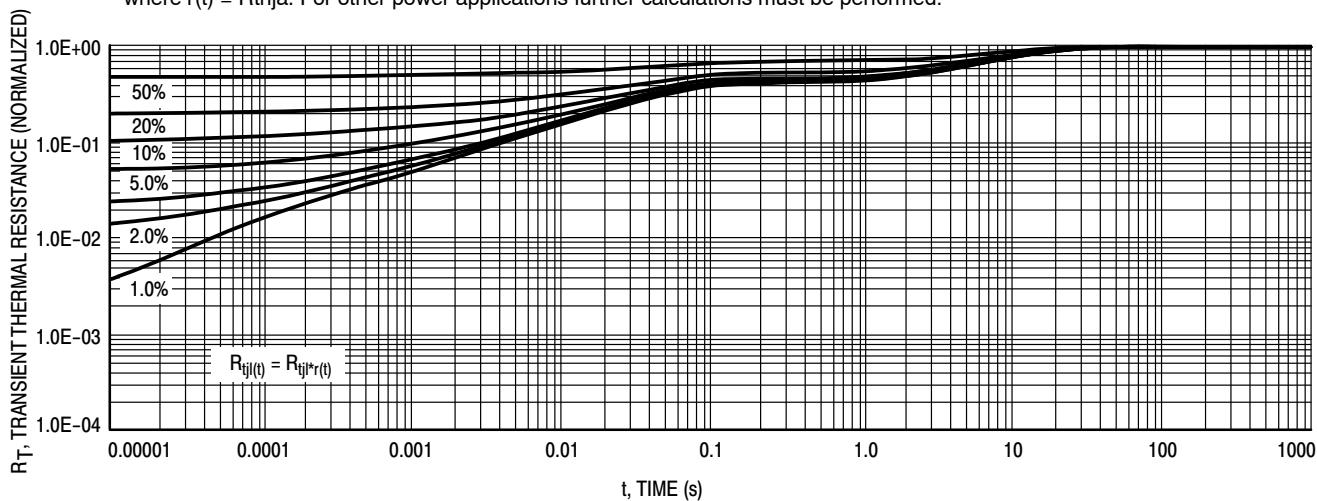
\* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of  $T_J$  therefore must include forward and reverse power effects. The allowable operating  $T_J$  may be calculated from the equation:  $T_J = T_{Jmax} - r(t)(P_f + P_r)$  where

$r(t)$  = thermal impedance under given conditions,

$P_f$  = forward power dissipation, and

$P_r$  = reverse power dissipation

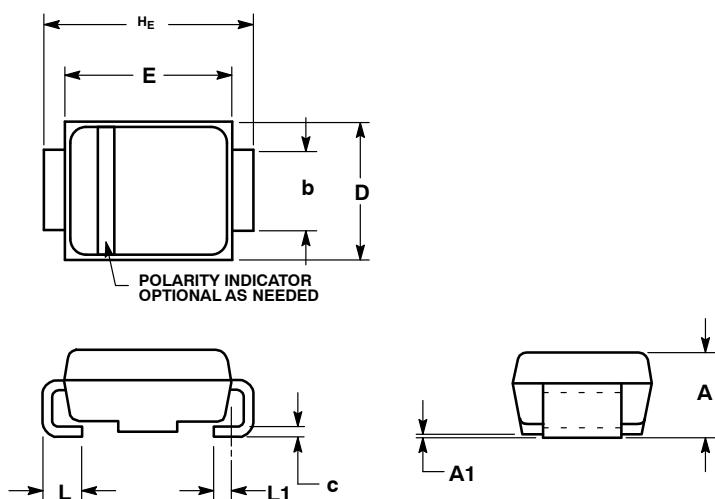
This graph displays the derated allowable  $T_J$  due to reverse bias under DC conditions only and is calculated as  $T_J = T_{Jmax} - r(t)P_r$ , where  $r(t) = R_{thja}$ . For other power applications further calculations must be performed.



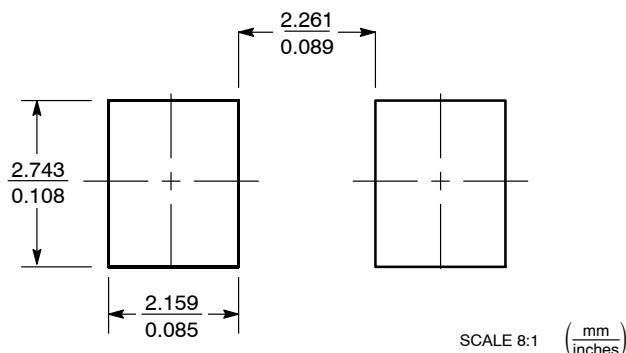


**SMB**  
CASE 403A-03  
ISSUE J

DATE 19 JUL 2012



## SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the [onsemi](#) Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

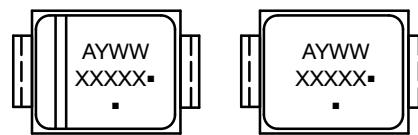
## NOTES:

- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
<b>A</b>	1.95	2.30	2.47	0.077	0.091	0.097
<b>A1</b>	0.05	0.10	0.20	0.002	0.004	0.008
<b>b</b>	1.96	2.03	2.20	0.077	0.080	0.087
<b>c</b>	0.15	0.23	0.31	0.006	0.009	0.012
<b>D</b>	3.30	3.56	3.95	0.130	0.140	0.156
<b>E</b>	4.06	4.32	4.60	0.160	0.170	0.181
<b>H<sub>E</sub></b>	5.21	5.44	5.60	0.205	0.214	0.220
<b>L</b>	0.76	1.02	1.60	0.030	0.040	0.063
<b>L<sub>1</sub></b>	0.51 INCH			0.0000 PEE		

## GENERIC MARKING DIAGRAM\*



### Polarity Band      Non-Polarity Band

XXXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
■ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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